

Double Side Aligner-EVG 620

DOUBLE SIDED MASK alignment system helps in high- precision single and double sided alignment. It also aids in wafer-to-wafer alignment for wafer bonding applications.

Specifications of the system:

- **Exposure modes:** hard, soft, vacuum contact
- **Separation distance:** 0-300 microns
- **Wafer thickness:** 0.1-10 mm
- **Lamp:** 500W Hg Lamp
- **Wavelength range:** 350-450 nm
- **Alignment accuracy:** 0.5 micron for top side and 1 micron for bottom side
- **Minimum feature size achievable:** 2 micron

Process Capabilities:

- **Substrates used:** Silicon, glass
- **Mask plate size:** 3", 5"
- **Substrate size:** 2", 4", quarter of a 2" wafer
- **Gases used:** GN2
- **Positive resist used:** Shipley's S1813 and S1805
- **Negative resists used:** SU8 2000.5, SU8 2050 and SU8 2100

